


Description: Giga-snaP BGA SMT Foot
 160 position male terminal pins to solder balls
 (1.0mm [0.039"] centers, 14x14 array)

Tolerances: diameters $\pm 0.03\text{mm}$ [± 0.001 "], PCB perimeters $\pm 0.13\text{mm}$ [± 0.005 "], PCB thicknesses $\pm 0.18\text{mm}$ [± 0.007 "], pitches (from true position) $\pm 0.08\text{mm}$ [± 0.003 "], all other tolerances $\pm 0.13\text{mm}$ [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

- ① Substrate: $1.59\text{mm} \pm 0.18\text{mm}$ [$0.0625" \pm 0.007$ "] FR4/G10 or equivalent high temp material.
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- $0.25\mu\text{m}$ [10μ "] Au over $1.27\mu\text{m}$ [50μ "] Ni (min.).
- ③ Balls: Eutectic 63/37 SnPb.

	SF-BGA160D-B-41 Drawing © 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Status: Released	Scale: 6:1	Rev: B
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